21/08/03
2003045994

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

162162

(43) International Publication Date
6 September 2002 (06.09.2002)

PCT

(10) International Publication Number
WO 02/069400 A1

(51) International Patent Classification[7]: H01L 23/02

(21) International Application Number: PCT/US02/05695

(22) International Filing Date: 25 February 2002 (25.02.2002)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:

60/272,239	27 February 2001 (27.02.2001)	US
10/081,490	22 February 2002 (22.02.2002)	US

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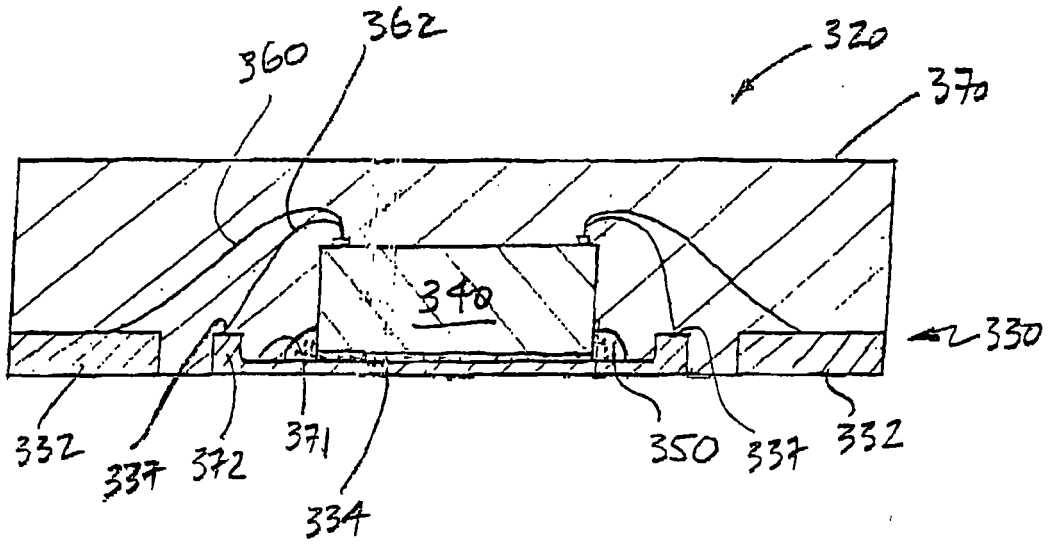
(81) Designated States *(national)*: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NO, NZ, OM, PH, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TN, TR, TT, TZ, UA, UG, UZ, VN, YU, ZA, ZM, ZW.

(84) Designated States *(regional)*: ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:
— *with international search report*
— *before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments*

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: PLASTIC SEMICONDUCTOR PACKAGE



WO 02/069400 A1

(57) Abstract: A lead frame (330) includes a die attach paddle (334) and leads (332), wherein a portion of the upper surface of the paddle includes recessed portion (371) or groove (474).

ACTION